

P-Channel 20V(D-S) MOSFET

Product summary		
V_{DS}	-20	V
$R_{DS(ON)}$ (at $V_{GS}=4.5V$)Typ.	99	$m\Omega$
$R_{DS(ON)}$ (at $V_{GS}=2.5V$) Typ.	138	$m\Omega$
$I_D(TA=25^\circ C)$	-1.5	A

Features

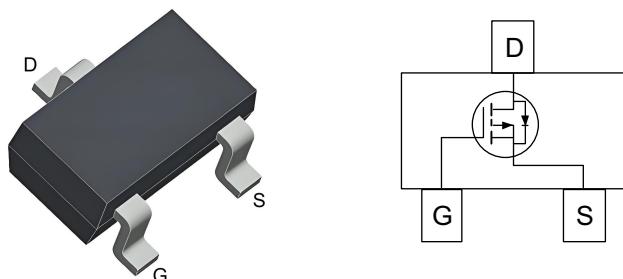
- Small package SOT-23
- Low Gate Charge
- RoHS Compliant

Applications

- Load Switch
- Power Management

Pin Configuration

SOT-23



Packing Information

Device	Marking	Reel Size	Tape Width	Quantity
ECG2301B	21B	7'	8mm	3000pcs

Absolute Maximum Ratings (at $TA=25^\circ C$ Unless Otherwise Noted)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	-20	V
V_{GS}	Gate-Source Voltage	± 10	V
I_D	Continuous Drain Current at $V_{GS}=10V$ ^A	$T_A=25^\circ C$	A
		$T_A=70^\circ C$	A
I_{DM}	Pulse Drain Current Tested ^B	-4	A
P_D	Power Dissipation	$T_A=25^\circ C$	W
T_J, T_{STG}	Junction and Storage Temperature Range	-55 to 150	°C

Thermal Characteristics

Symbol	Parameter	Typical	Units
$R_{\theta JA}$	Thermal Resistance-Junction to ambient ^A	179	°C/W

Electrical Characteristics (at $T_J = 25^\circ\text{C}$ Unless Otherwise Noted)

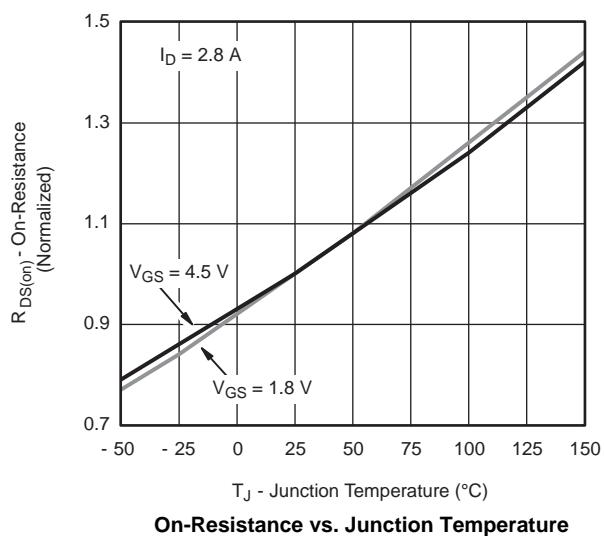
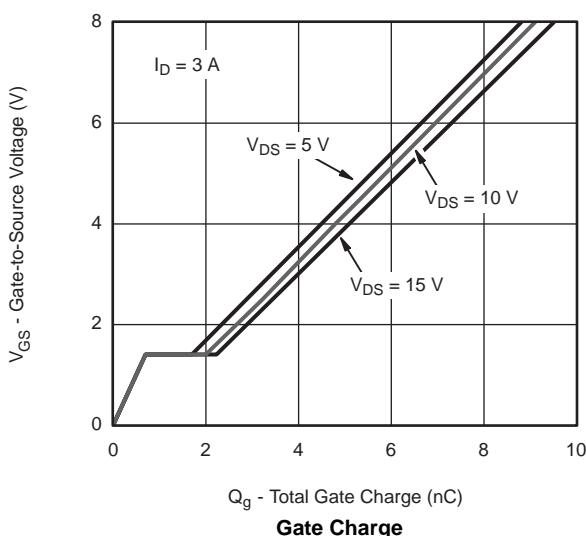
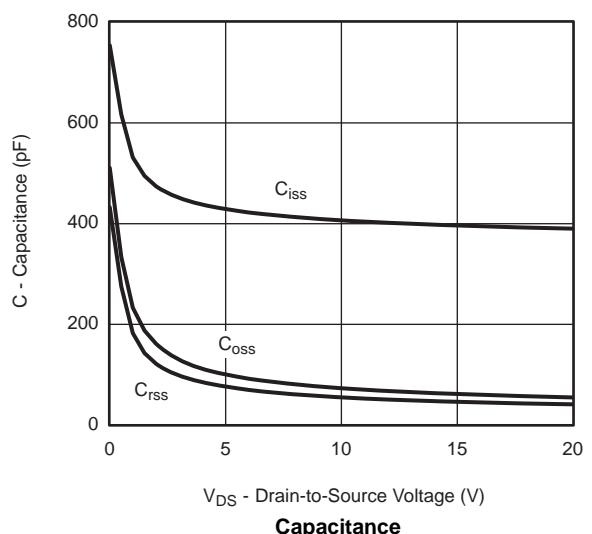
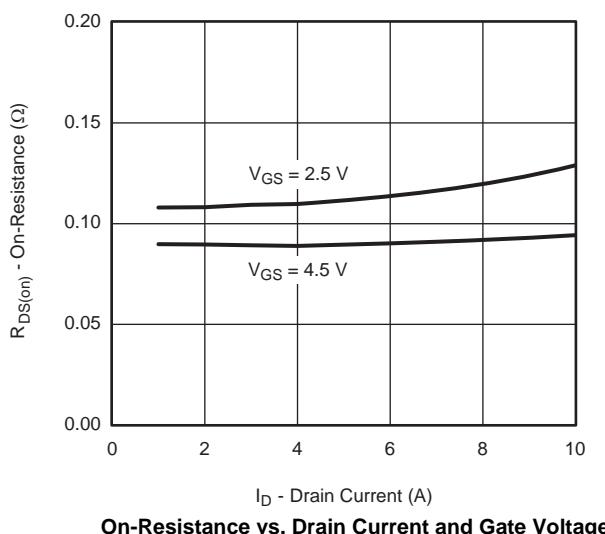
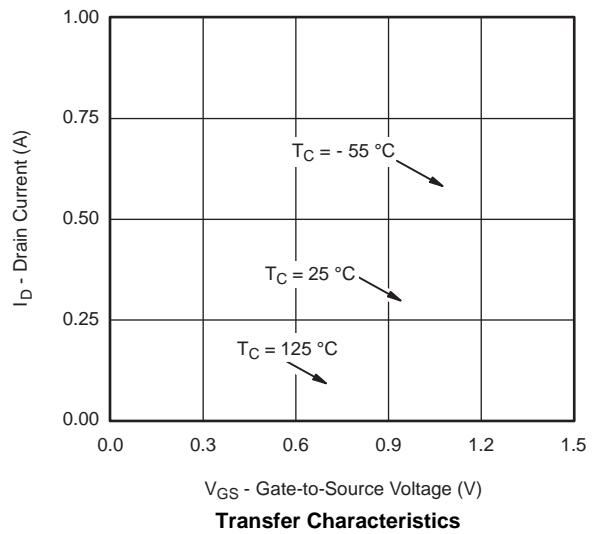
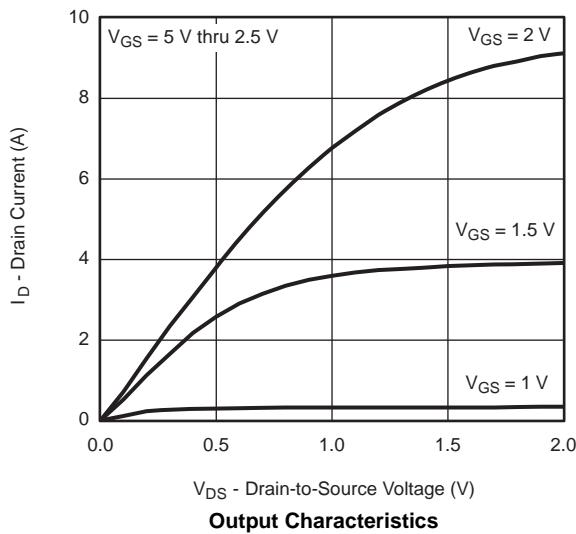
Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
Static Parameters						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=-250\mu\text{A}$	-20	--	--	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{\text{DS}}=-16\text{V}, V_{\text{GS}}=0\text{V}$	--	--	-1	μA
I_{GSS}	Gate-Body Leakage Current	$V_{\text{DS}}=0\text{V}, V_{\text{GS}}=\pm 12\text{V}$	--	--	± 100	nA
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=-250\mu\text{A}$	-0.5	-0.7	-1.0	V
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance ^B	$V_{\text{GS}}=-4.5\text{V}, I_{\text{D}}=-0.5\text{A}$	--	99	145	$\text{m}\Omega$
		$V_{\text{GS}}=-2.5\text{V}, I_{\text{D}}=-0.5\text{A}$	--	138	195	$\text{m}\Omega$
V_{SD}	Forward Voltage	$I_{\text{SD}}=-0.8\text{A}, V_{\text{GS}}=0\text{V}$	--	-0.7	-1.3	V
Dynamic Parameters ^C						
C_{iss}	Input Capacitance	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=-10\text{V}$ $f=1\text{MHz}$	--	405	--	pF
C_{oss}	Output Capacitance		--	75	--	pF
C_{rss}	Reverse Transfer Capacitance		--	55	--	pF
Q_g	Total Gate Charge	$V_{\text{DS}}=-10\text{V}, I_{\text{D}}=-1.5\text{A}$ $V_{\text{GS}}=-4.5\text{V}$	--	5.8	--	nC
Q_{gs}	Gate-Source Charge		--	0.8	--	nC
Q_{gd}	Gate-Drain Charge		--	1.4	--	nC
Switching Parameters						
$t_{\text{D}(\text{on})}$	Turn-on Delay Time	$V_{\text{DS}}=-10\text{V}, I_{\text{D}}=-1\text{A}$ $R_L=10\Omega, R_G=1\Omega,$ $V_{\text{GS}}=-4.5\text{V}$	--	12	--	nS
t_r	Turn-on Rise Time		--	33	--	nS
$t_{\text{D}(\text{off})}$	Turn-off Delay Time		--	30	--	nS
t_f	Turn-off Fall Time		--	11	--	nS

A. The data tested by surface mounted on a 1 inch x 1 inch FR-4 board with 2OZ copper.

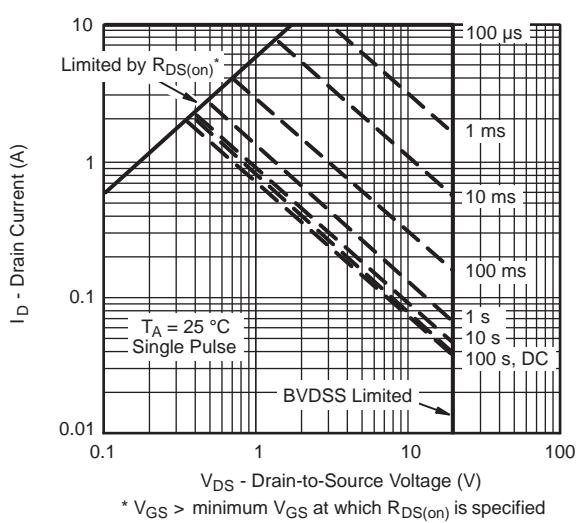
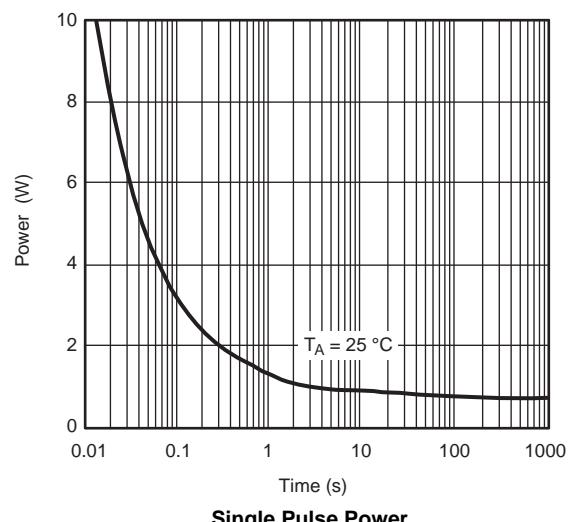
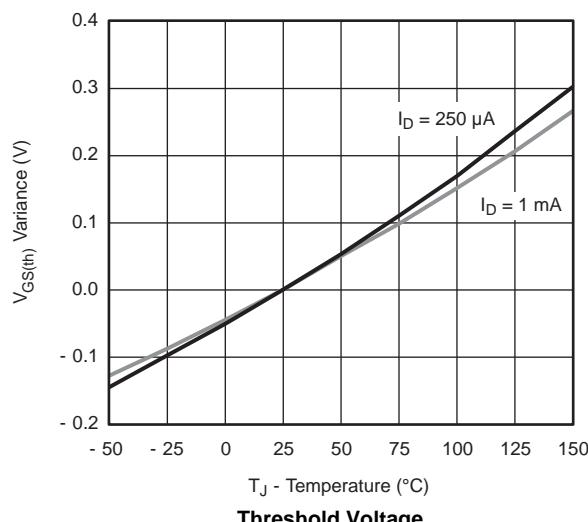
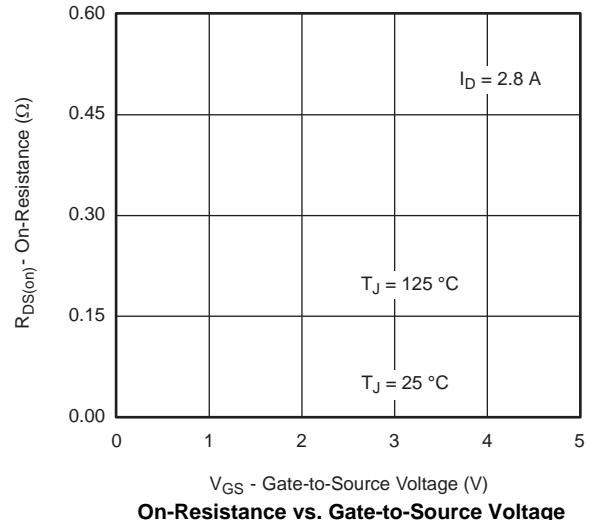
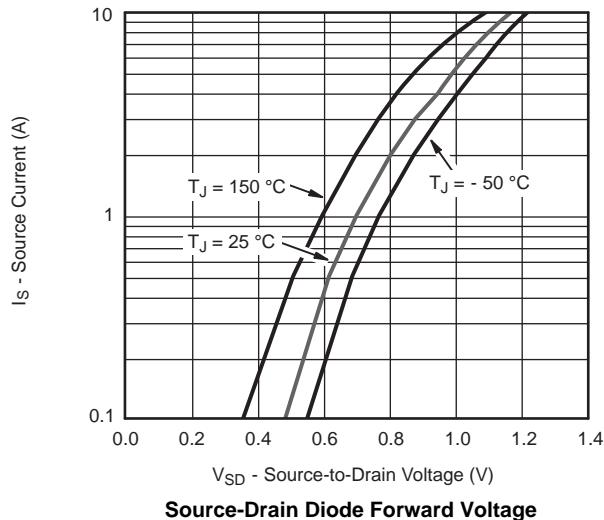
B. Pulse Test: Pulse Width $\leq 300\text{us}$, Duty cycle $\leq 2\%$.

C. Guaranteed by design, not subject to production testing.

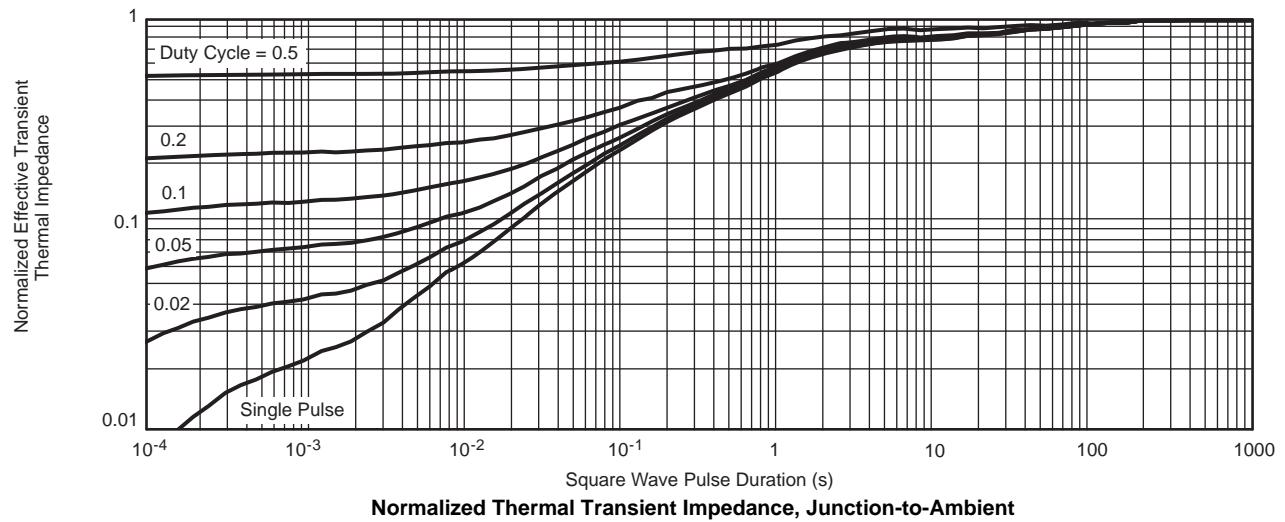
Typical Characteristics



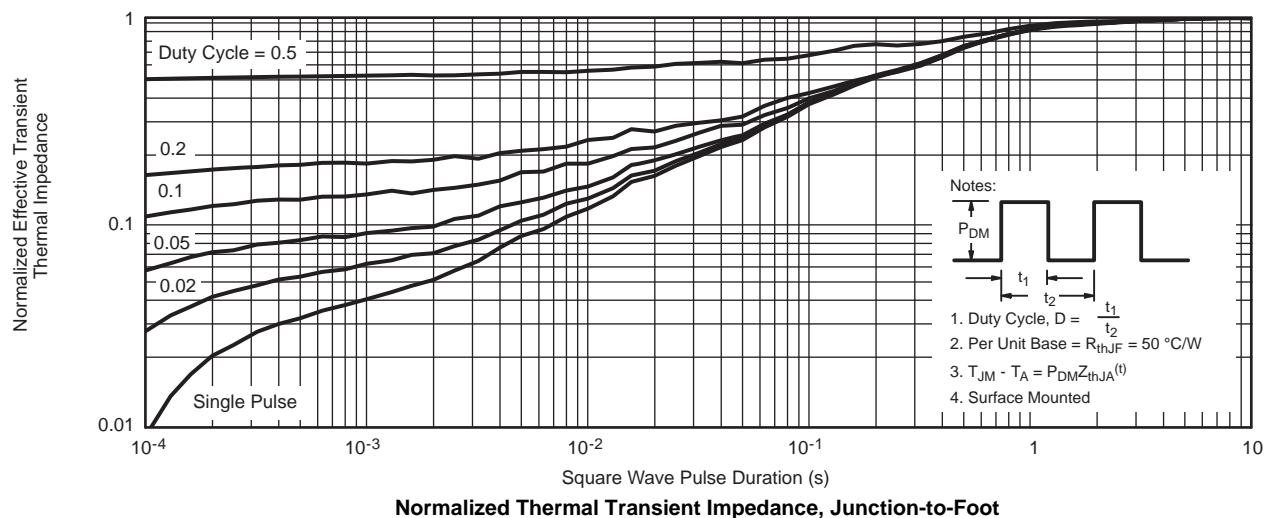
Typical Characteristics



Typical Characteristics

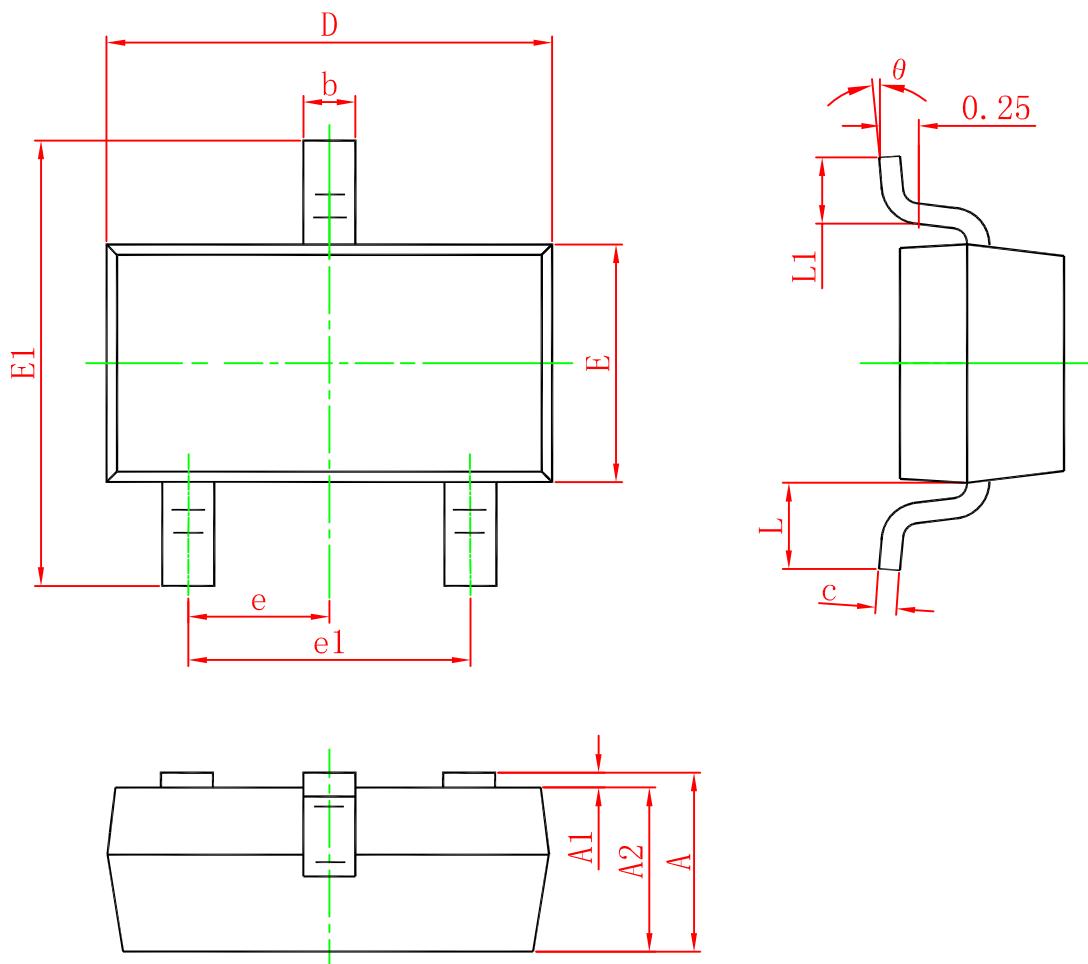


Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

SOT-23 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP.		0.037 TYP.	
e1	1.800	2.000	0.071	0.079
L	0.550 REF.		0.022 REF.	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°